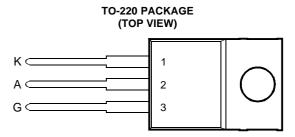
- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 200 μA



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	TIC106D		400	
Repetitive peak off-state voltage (see Note 1)	TIC106M	V	600	V
Repetitive peak off-state voltage (see Note 1)	TIC106S	V _{DRM}	700	v
	TIC106N		800	
	TIC106D		400	
	TIC106M	N	600	V
Repetitive peak reverse voltage	TIC106S	V _{RRM}	700	v
	TIC106N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)	I _{T(RMS)}	5	А	
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			3.2	А
(see Note 3)			3.2	A
Surge on-state current (see Note 4)			30	А
Peak positive gate current (pulse width \leq 300 µs)			0.2	А
Peak gate power dissipation (pulse width \leq 300 µs)			1.3	W
Average gate power dissipation (see Note 5)			0.3	W
Operating case temperature range			-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds			230	°C

NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 k Ω .

3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.

4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

5. This value applies for a maximum averaging time of 20 ms.

^{2.} These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.

TIC106 SERIES SILICON CONTROLLED RECTIFIERS

PARAMETER			TEST CONDITIO	NS	MIN	MAX	UNIT	
I _{DRM}	Repetitive peak off-state current	V_{D} = rated V_{DRM}	$R_{GK} = 1 \ k\Omega$	T _C = 110°C			400	μA
I _{RRM}	Repetitive peak reverse current	V_R = rated V_{RRM}	$I_{\rm G}=0$	T _C = 110°C			1	mA
I _{GT}	Gate trigger current	V _{AA} = 6 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		60	200	μΑ
V _{GT}	Gate trigger voltage	V _{AA} = 6 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	$T_{C} = -40^{\circ}C$			1.2	
		V _{AA} = 6 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ		0.4	0.6	1	V
		V _{AA} = 6 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	T _C = 110°C	0.2			
Ι _Η	Holding current	$V_{AA} = 6 V$ Initiating I _T = 10 mA	$R_{GK} = 1 \ k\Omega$	$T_{C} = -40^{\circ}C$			8	mA
		$V_{AA} = 6 V$ Initiating I _T = 10 mA	$R_{GK} = 1 \ k\Omega$				5	ШA
V_{TM}	Peak on-state voltage	I _{TM} = 5 A	(See Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	R_{GK} = 1 k Ω	T _C = 110°C		10		V/µs

electrical characteristics at 25°C case temperature (unless otherwise noted)

NOTE 6: This parameter must be measured using pulse techniques, $t_p = 300 \ \mu s$, duty cycle $\le 2 \ \%$. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
R_{\thetaJC}	Junction to case thermal resistance			3.5	°C/W
R _{θJA}	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	ТҮР	MAX	UNIT
t _{gt}	Gate-controlled turn-on time	I _T = 5 A	I _G = 10 mA	See Figure 1		1.75		μs
	Circuit-commutated	Ι _τ = 5 Α	$I_{G} = 10 \text{ mA}$	See Figure 2				
tq	turn-off time	I _{RM} = 8 A	6	<u> </u>		7.7		μs

TIC106 SERIES SILICON CONTROLLED RECTIFIERS

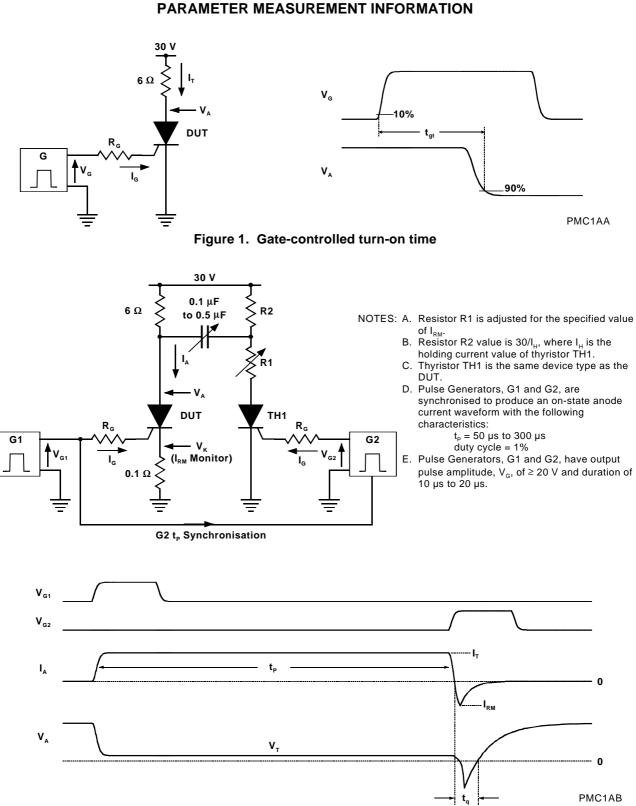


Figure 2. Circuit-commutated turn-off time